

DATA SHEET

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SEMICONDUCTOR COMPANY
MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.

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AN17821A

BTL 5.0 W × 2-channel power amplifier with standby function and volume function

■ Applications

- ICs for low frequency amplifier

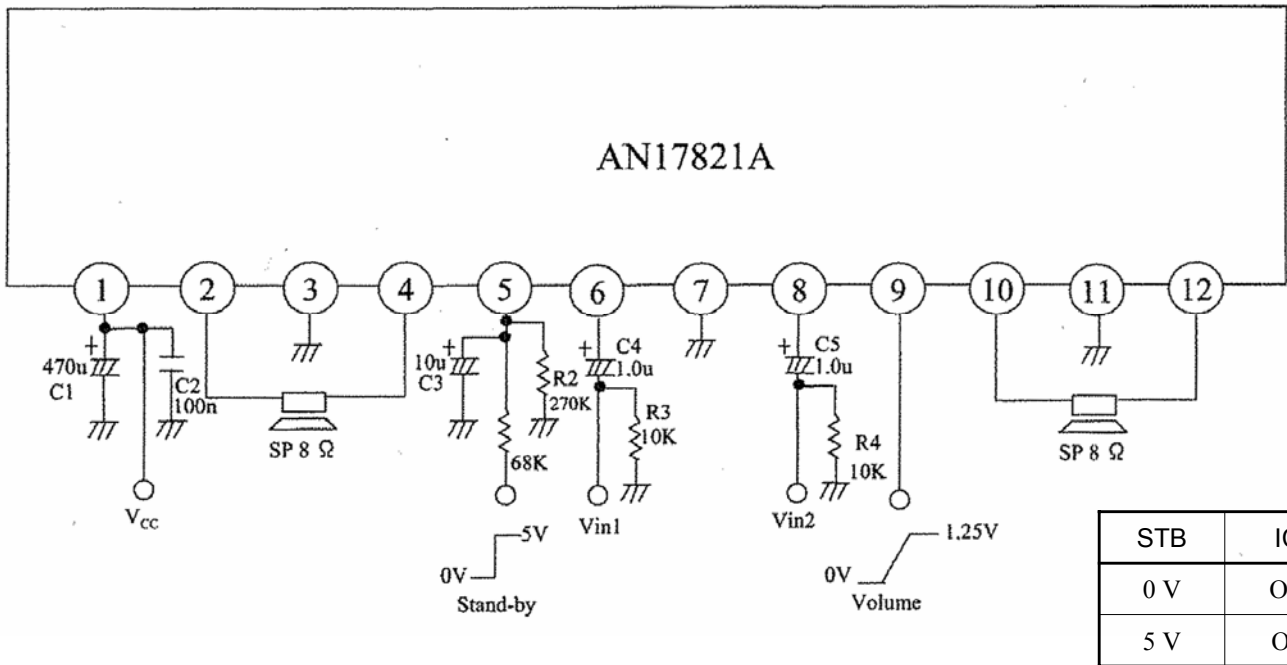
■ Package

- SIL 12-pin plastic package (power type with fin)

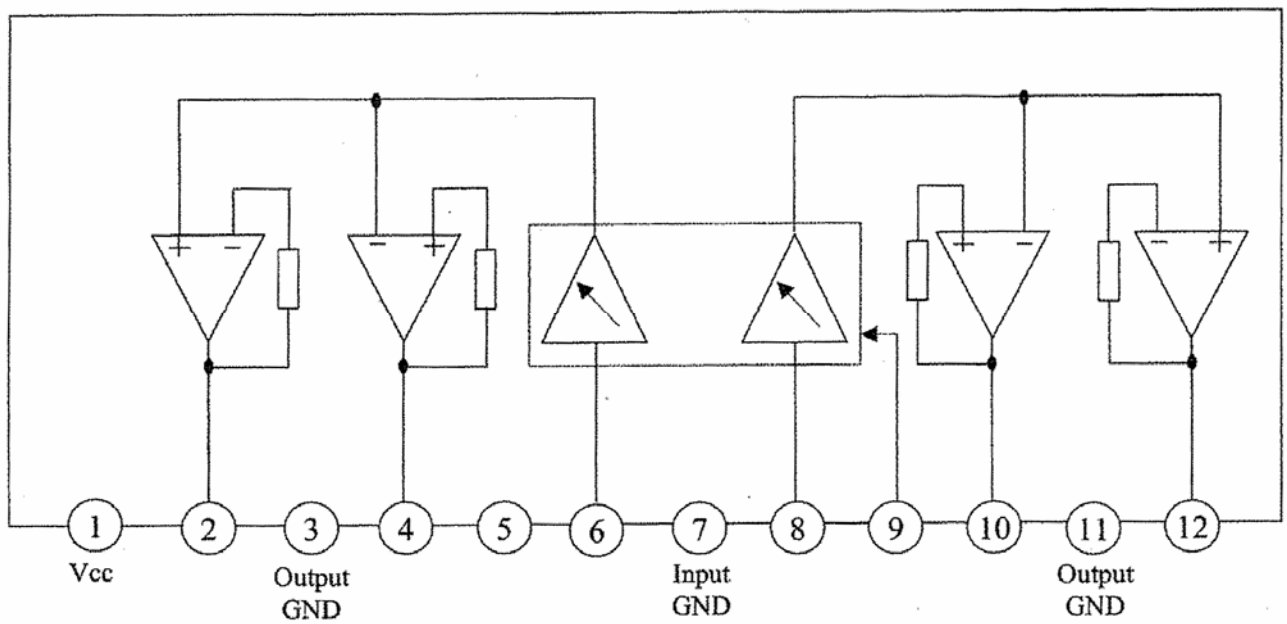
■ Type

- Silicon monolithic bipolar IC

■ Application Circuit Example



■ Block Diagram



■ Pin Descriptions

Pin No.	Description	Pin No.	Description
1	V _{CC}	7	GND (input)
2	Channel 1 output (+)	8	Channel 2 input
3	GND (channel 1 output)	9	Volume
4	Channel 1 output (-)	10	Channel 2 output (-)
5	Standby	11	GND (channel 2 output)
6	Channel 1 input	12	Channel 2 output (+)

■ Absolute Maximum Ratings

A No.	Parameter	Symbol	Rating	Unit	Note
1	Supply voltage	V _{CC}	14.4	V	*1
2	Supply current	I _{CC}	2.0	A	
3	Power dissipation	P _D	1.92	W	*2
4	Storage temperature	T _{stg}	-55 to +150	°C	*3
5	Operating ambient temperature	T _{opr}	-25 to +70	°C	*3
6	Operating ambient atmospheric pressure	P _{opr}	$1.013 \times 10^5 \pm 0.61 \times 10^5$	Pa	
7	Operating constant gravity	G _{opr}	9 810	m/S ²	
8	Operating shock	S _{opr}	4 900	m/S ²	

Note) *1: No signal input.

*2: T_a = 70°C.

*3: Expect for the storage temperature and operating ambient temperature, all ratings are for T_a = 25°C.

■ Operating Supply Voltage Range

Parameter	Symbol	Range	Unit	Note
Supply voltage range	V _{CC}	3.5 to 13.5	V	

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